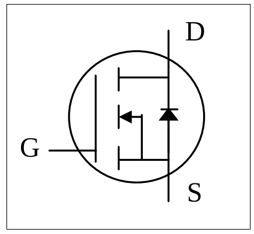
N-CHANNEL ENHANCEMENT MODE POWER MOSFET

PRODUCT SUMMARY

Simple Drive Requirement
Low On-resistance
Fast Switching Characteristic

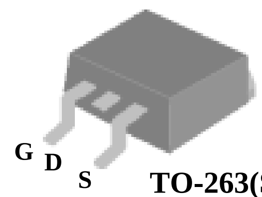


BV_{DSS}	80V
$R_{DS(ON)}$	13mΩ
I_D	75A

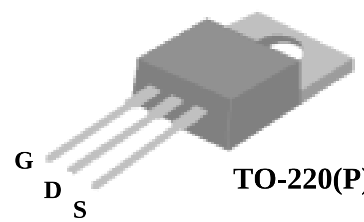
DESCRIPTION

The Advanced Power MOSFETs from Silicon Standard Corp. provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-263 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters. The through-hole version (SSM85T08GP) are available for low-profile applications.



TO-263(S)



TO-220(P)

Pb-free; RoHS-compliant

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V	75	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V	48	A
I_{DM}	Pulsed Drain Current[1]	260	A
P_D@T_C=25℃	Total Power Dissipation	138	W
	Linear Derating Factor	1.11	W/℃
E_{AS}	Single Pulse Avalanche Energy[3]	450	mJ
I_{AR}	Avalanche Current	30	A
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

THERMAL DATA

Symbol	Parameter		Value	Units
Rthj-c	Thermal Resistance Junction-case	Max.	0.9	℃/W
Rthj-a	Thermal Resistance Junction-ambient	Max.	62	℃/W

ELECTRICAL CHARACTERISTICS

@T_J=25 ^oC (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=1mA	80	-	-	V
$\Delta BV_{DSS}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to 25℃, I_D=1mA	-	0.09	-	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V, I_D=45A	-	-	13	mΩ
		V_{GS}=4.5V, I_D=25A	-	-	18	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	1	-	3	V
g_{fs}	Forward Transconductance	V_{DS}=10V, I_D=45A	-	70	-	S
I_{DSS}	Drain-Source Leakage Current (T_j=25^{o}C)	V_{DS}=80V, V_{GS}=0V	-	-	10	uA
	Drain-Source Leakage Current (T_j=150^{o}C)	V_{DS}=64V ,V_{GS}=0V	-	-	100	uA
I_{GSS}	Gate-Source Leakage	V_{GS}= ±20V	-	-	±100	nA
Q_g	Total Gate Charge[2]	I_D=45A	-	63	100	nC
Q_{gs}	Gate-Source Charge	V_{DS}=64V	-	23	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=4.5V	-	38	-	nC
$t_{d(on)}$	Turn-on Delay Time[2]	V_{DS}=40V	-	30	-	ns
t_r	Rise Time	I_D=45A	-	100	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=10Ω,V_{GS}=10V	-	144	-	ns
t_f	Fall Time	R_D=0.89Ω	-	173	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	6300	10080	pF
C_{oss}	Output Capacitance	V_{DS}=25V	-	670	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	350	-	pF
R_g	Gate Resistance	f=1.0MHz	-	1.1	1.7	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S=45A, V_{GS}=0V	-	-	1.3	V
t_{rr}	Reverse Recovery Time[2]	I_S=20A, V_{GS}=0V	-	47	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt=100A/µs	-	86	-	nC

Notes:

1.Pulse width limited by safe operating area.

2.Pulse width $\leq$300us , duty cycle $\leq$2%.

3.Starting T_j=25^{o}C , V_{DD}=30V , L=1mH , R_G=25Ω , I_{AS}=30A.

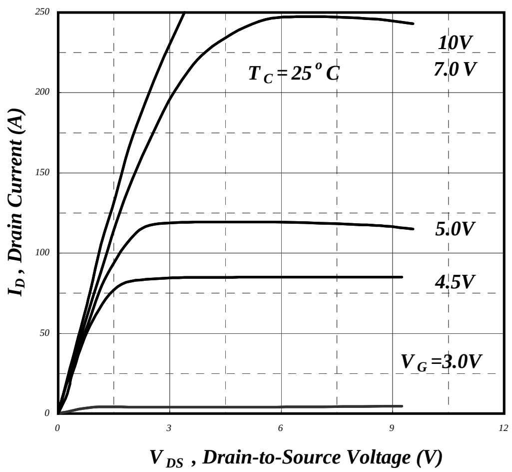


Fig 1. Typical Output Characteristics

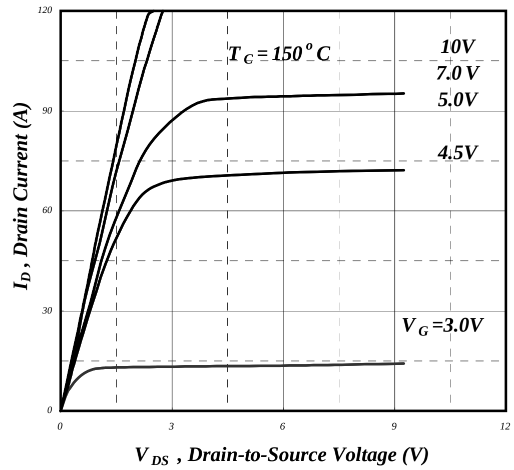


Fig 2. Typical Output Characteristics

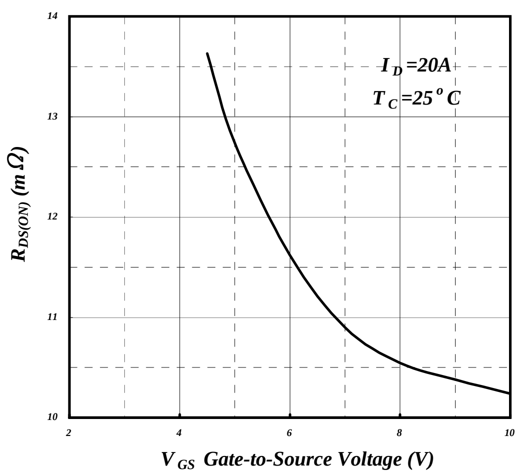


Fig 3. On-Resistance v.s. Gate Voltage

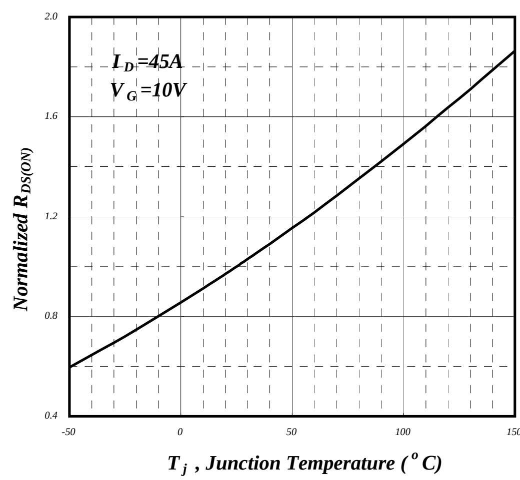


Fig 4. Normalized On-Resistance v.s. Junction Temperature

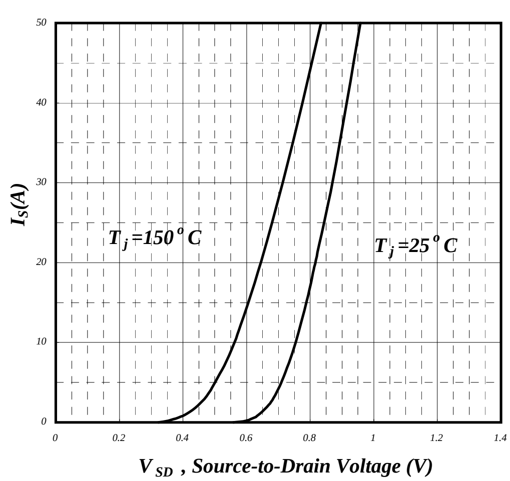


Fig 5. Forward Characteristic of Reverse Diode

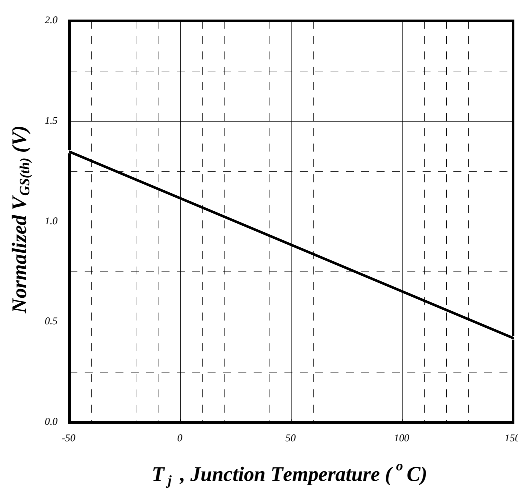


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

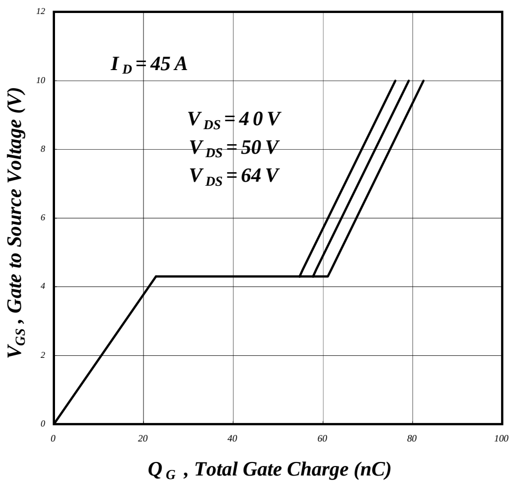


Fig 7. Gate Charge Characteristics

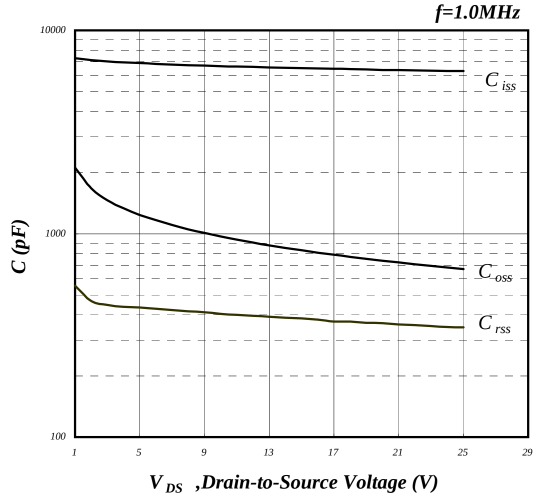


Fig 8. Typical Capacitance Characteristics

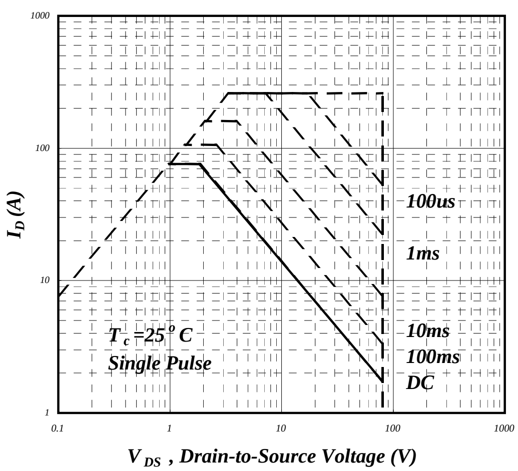


Fig 9. Maximum Safe Operating Area

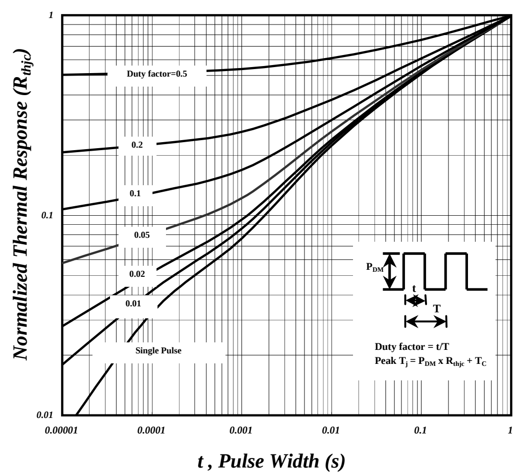


Fig 10. Effective Transient Thermal Impedance

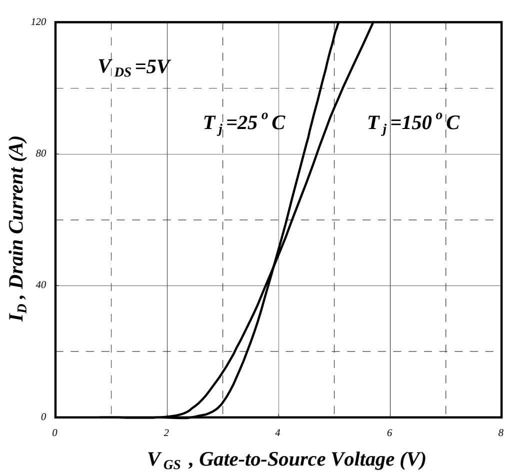


Fig 11. Transfer Characteristics

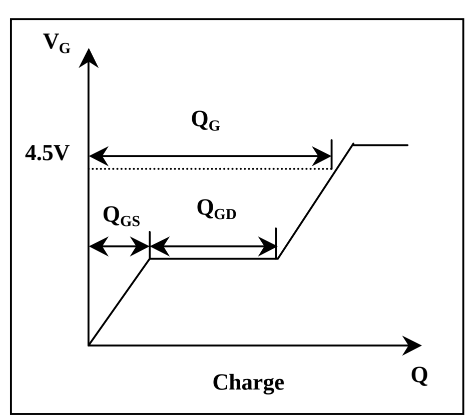


Fig 12. Gate Charge Waveform